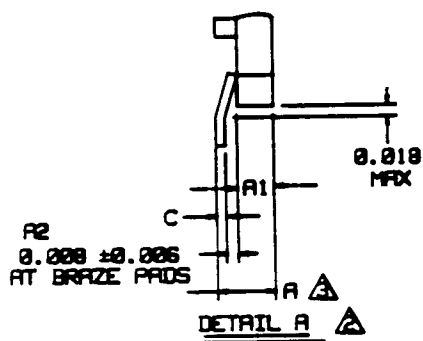


	.030	C	A	B
	.009	C		



JEDEC SOLID STATE PRODUCT OUTLINES	TITLE: CERAMIC QUADPACK FAMILY .025 INCH LEAD SPACING	ISSUE B	DATE 9-89	MO - 090 AA - AF	SHEET 1 OF 4
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SYMBOL	VARIATIONS											(DIMENSIONS IN INCHES)			
	AA			NOTE	AB			NOTE	AC			NOTE			
	MIN	NOM	MAX		MIN	NOM	MAX		MIN	NOM	MAX				
A	—		.130	3	—		.130	3	—	—	.130	3			
A1	—		.105		—		.105		—	—	.105				
B	.006	.000	.012		.006	.000	.013		.006	.000	.010				
C	.004	.006	.000	5	.004	.006	.000	5	.004	.006	.000	5			
D,E	1.100	1.450	1.530		1.400	1.510	1.525		1.500	1.600	1.615				
D1,E1	.635	.650	.660		.935	.950	.960		1.035	1.050	1.065				
D2,E2		.500 BSC				.800 BSC				.875 BSC					
D3,E3		.250 BSC				.400 BSC				.438 BSC					
L	.250		—	6	.250		—	6	.250		—	6			
N		84				132				144					
ND		21			7	33			7	36			7		
NOTE															
	AD			NOTE	AE			NOTE	AF						
	MIN	NOM	MAX		MAX	NOM	MIN		MAX	NOM	MIN				
A	—	—	.130	3	—		.130	3	—	—	.135	3			
A1	—	—	.105		—		.105		—	—	.120				
B	.006	.000	.010		.006	.000	.010		.000	.010	.013				
C	.004	.006	.000	5	.004	.006	.000	5	.005	.007	.009	5			
D,E	1.600	1.910	1.925		1.800	1.900	1.915		1.420	1.450	1.465				
D1,E1	1.135	1.150	1.165		1.335	1.350	1.365		.735	.750	.765				
D2,E2		1.050 BSC				1.200 BSC				.600 BSC					
D3,E3		.525 BSC				.600 BSC				.300 BSC					
L	.250	—	—	6	.250	—	—	6	.250	—	—	6			
N		172				196				100					
ND		43			7	49			7	25			7		
NOTE															
REF.															
ISSUE															
JEDEC SOLID STATE PRODUCT OUTLINES			TITLE: CERAMIC QUADPACK FAMILY .025 INCH LEAD SPACING				ISSUE B		DATE 9-89		MO - 090 AA - AF		SHEET 2 OF 4		

SYMBOL	VARIATIONS (DIMENSIONS IN MILLIMETERS)											
	AA			NOTE	AB			NOTE	AC			NOTE
	MIN	NOM	MAX		MIN	NOM	MAX		MIN	NOM	MAX	
A	—		3.30	3	—		3.30	3	—	—	3.30	3
AI	—		2.67		—		2.67		—	—	2.67	
B	.152	.203	.305		.152	.203	.330		.152	.203	.254	
C	.102	.152	.203	5	.102	.152	.203	5	.102	.152	.203	5
D,E	29.97	36.83	38.86		37.59	38.35	38.74		40.13	40.64	41.02	
D1,E1	16.13	16.51	16.76		23.75	24.13	24.38		26.29	26.67	27.05	
D2,E2	12.70 BSC				20.32 BSC				22.23 BSC			
D3,E3	6.35 BSC				10.16 BSC				11.11 BSC			
L	6.35		—	6	6.35		—	6	6.35		—	6
N		84				132				144		
ND		21				33				36		
NOTE												
	AD			NOTE	AE			NOTE	AF			
	MIN	NOM	MAX		MAX	NOM	MIN		MAX	NOM	MIN	
A	—	—	3.30	3	—	—	3.30	3	—	—	3.43	3
AI	—	—	2.67		—	—	2.67		—	—	3.048	
B	.152	.203	2.54		.152	.203	.254		.203	.254	.330	
C	.102	.152	.203	5	.102	.152	.203	5	.127	.178	.229	5
D,E	42.67	45.97	46.34		47.75	48.26	48.64		36.87	36.83	37.21	
D1,E1	28.83	29.91	29.58		33.91	34.29	34.67		18.67	19.05	19.43	
D2,E2	26.67 BSC				38.84 BSC				15.24 BSC			
D3,E3	13.34 BSC				15.24 BSC				7.62 BSC			
L	6.35	—	—	6	6.35	—	—	6	6.35	—	—	6
N		172				196				100		
ND		43				49				25		
NOTE												
REF.												
ISSUE												
JEDEC SOLID STATE PRODUCT OUTLINES			TITLE: CERAMIC QUADPACK FAMILY .025 INCH LEAD SPACING				ISSUE B		DATE 9-89		MO - 090 AA - AF	
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Notes:

1. An index mark shall be located within the shaded area shown.
2. Generic lead attach dogleg depiction. May be flat lead configuration.
3. Includes lead attach dogleg height and lid height, whichever is greater.
4. Corner chamfers and/or notches are optional, but any index corner shall be per JEDEC Pub. 95 leadless chip carrier indexing.
5. Dimension D1: Exclusive of package anomalies (ceramic particles, etc). Such anomalies shall not exceed .010 inch.
6. Dimension N: Number of terminals.
7. Dimension ND: Number of terminals per package edge.
8. Controlling dimension: Inch.
9. Regardless of the virtual length, the .020 limit ensures an accurate, square trim for subsequent lead forming tool registration.
10. Dimensioning is per ANSI Y14.5M - 1982.

Application notes for all lead finishes:

1. Lead dimension must be within tabulated callouts before solder dip or tin plate.
2. All leadfinish thicknesses must be per MIL-M-38510, or other procurement specification.
3. The increase in the B dimension, as a result of solder finishes, does not change the positional tolerance, .009, which is applied at MMC of .010 (for RC-FE). The total envelope that the leads must simultaneously reside in is unchanged and remains at .019 (.009 + .010 = .019).

General user application notes:

1. Navy specification W565356 requires lead width to be .009 max. Low side dimensions should be considered in individual designs.
2. Solder finishes may mask the true width of the lead. Consider the board attached reflowed assembly when performing lead width inspection with solder finishes.
3. Navy format "E" SEM modules restrict overall package dimension A to .115 max.
4. Dimension R2 (dogleg height) seems to allow a great variation to apply to a single package. Such a variation within a single package cannot occur or leadform/leadfoot location will be drastically affected.

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